

SOT1427-1

plastic low profile fine-pitch ball grid array package; 159 balls
8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA159
Package type industry code	LFBGA159
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-7-2014

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.9	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	1.25	-	1.35	1.5	mm
e	nominal pitch	-	-	0.8	-	m
n ₂	actual quantity of termination	-	-	159	-	



2. Package outline

LFBGA159: plastic low profile fine-pitch ball grid array package; 159 balls SOT1427-1

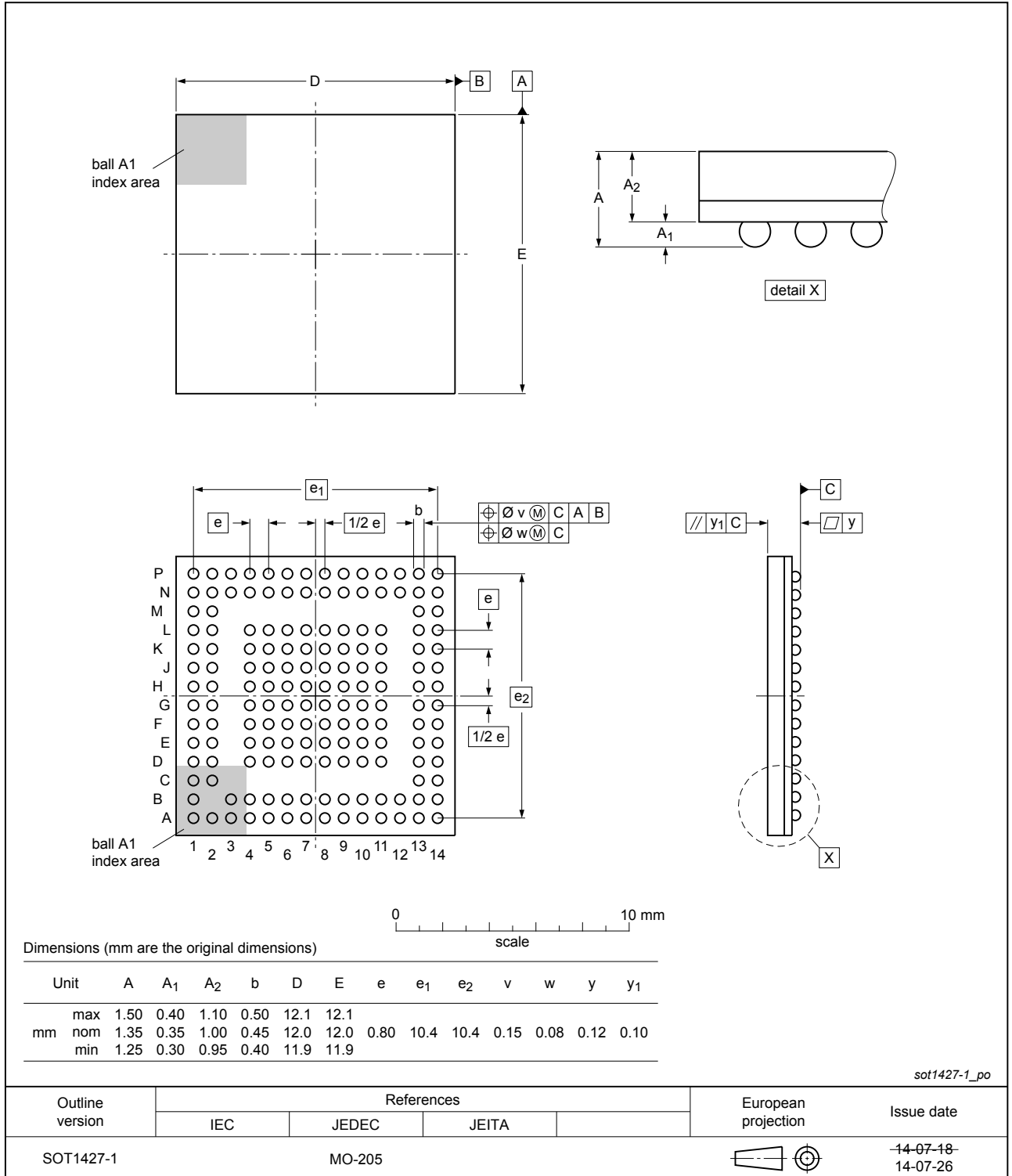
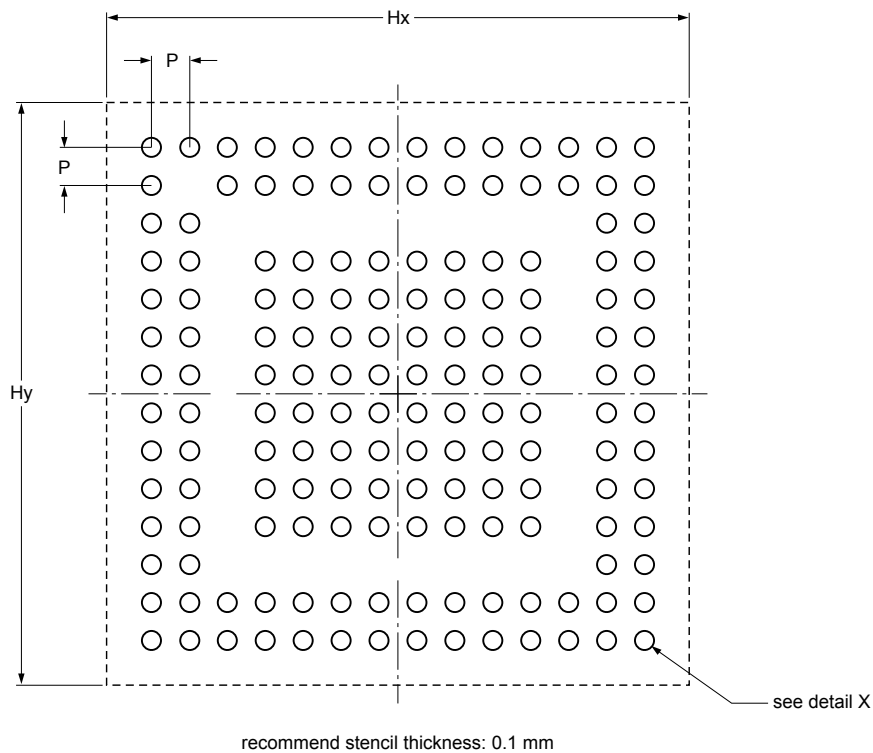


Fig. 1. Package outline LFBGA159 (SOT1427-1)






3. Soldering

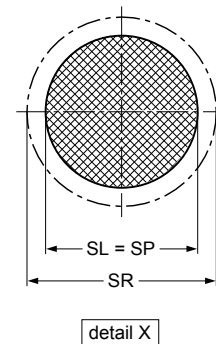
Footprint information for reflow soldering of LFBGA159 package

SOT1427-1



see detail X

-  solder land (SL)
-  solder paste deposit (SP)
-  solder land plus solder paste
-  solder resist opening (SR)
-  occupied area



Dimensions in mm

P	SL	SP	SR	Hx	Hy
0.8	0.4	0.4	0.5	12.3	12.3

Issue date ~~14-11-28~~
15-06-15

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Fig. 2. Reflow soldering footprint for LFBGA159 (SOT1427-1)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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